Introduction

In the target devices (RL78/F13, F14), multiple interrupt sources are shared in one interrupt vector table address as shown in the following Table 1-1. When using multiple interrupt sources together, software processing must determine which interrupt occurred in the interrupt processing or both interrupts occurred.

This application note describes how to determine the interrupt source when using both interrupt sources simultaneously.

Table 1-1 List of Multiple Interrupt Sources that are Shared in One Interrupt Vector Table

<table>
<thead>
<tr>
<th>Vector Table Address</th>
<th>Interrupt Source Name</th>
<th>Trigger</th>
<th>Reference Section</th>
</tr>
</thead>
<tbody>
<tr>
<td>0010H</td>
<td>INTP4</td>
<td>Pin input edge detection 4</td>
<td>Section 1.1</td>
</tr>
<tr>
<td></td>
<td>INTPM</td>
<td>Stack pointer overflow/underflow detection</td>
<td></td>
</tr>
<tr>
<td>0012H</td>
<td>INTP5</td>
<td>Pin input edge detection 5</td>
<td>Section 1.2</td>
</tr>
<tr>
<td></td>
<td>INTCMP0</td>
<td>Comparator detection 0</td>
<td></td>
</tr>
<tr>
<td>0014H</td>
<td>INTP13</td>
<td>Pin input edge detection 13</td>
<td>Section 1.3</td>
</tr>
<tr>
<td></td>
<td>INTCLM</td>
<td>Main clock or PLL clock stopn detection</td>
<td></td>
</tr>
<tr>
<td>002AH</td>
<td>INTP8</td>
<td>Pin input edge detection 8</td>
<td>Section 1.4</td>
</tr>
<tr>
<td></td>
<td>INTRTC</td>
<td>RTC pretimed signal or alarm match detection</td>
<td></td>
</tr>
<tr>
<td>0036H</td>
<td>INTP6</td>
<td>Pin input edge detection 6</td>
<td>Cannot identify both interrupt sources.</td>
</tr>
<tr>
<td></td>
<td>INTTM11H</td>
<td>Upper 8-bit interval timer interrupt of TAU1 channel 1</td>
<td></td>
</tr>
<tr>
<td>0038H</td>
<td>INTP7</td>
<td>Pin input edge detection 7</td>
<td></td>
</tr>
<tr>
<td></td>
<td>INTTM13H</td>
<td>Upper 8-bit interval timer interrupt of TAU1 channel 3</td>
<td></td>
</tr>
<tr>
<td>003AH</td>
<td>INTP9</td>
<td>Pin input edge detection 9</td>
<td></td>
</tr>
<tr>
<td></td>
<td>INTTM01H</td>
<td>Upper 8-bit interval timer interrupt of TAU0 channel 1</td>
<td></td>
</tr>
<tr>
<td>003CH</td>
<td>INTP10</td>
<td>Pin input edge detection 10</td>
<td></td>
</tr>
<tr>
<td></td>
<td>INTTM03H</td>
<td>Upper 8-bit interval timer interrupt of TAU0 channel 3</td>
<td></td>
</tr>
<tr>
<td>004AH</td>
<td>INTP11</td>
<td>Pin input edge detection 11</td>
<td>Cannot use both simultaneously.</td>
</tr>
<tr>
<td></td>
<td>INTLIN0WUP</td>
<td>LIN0 reception pin input detection</td>
<td></td>
</tr>
<tr>
<td>0064H</td>
<td>INTP12</td>
<td>Pin input edge detection 12</td>
<td></td>
</tr>
<tr>
<td></td>
<td>INTLIN1WUP</td>
<td>LIN1 reception pin input detection</td>
<td></td>
</tr>
</tbody>
</table>

Note: It depends on the product. For details, show the user’s manual: hardware.
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1. **Interrupt Source Determination Procedure**

In the target devices (RL78/F13, F14), multiple interrupt sources are shared in one interrupt vector table address. When using multiple interrupt sources together, software processing must determine which interrupt occurred in the interrupt processing or both interrupts occurred. The following describes how to determine the interrupt source when using both interrupt sources simultaneously.

1.1 **Determination between INTP4 and INTSPM**

Figure 1-1 shows an interrupt processing example in case of both INTP4 (Pin input edge detection 4) and INTSPM (Stack pointer overflow/underflow) are enabled.

Interrupt by INTP4 can be determined from INTFLG00 bit of INTFLG0 (Interrupt source determination flag register 0). And interrupt by INTSPM can be determined by reading stack pointer from user software.

**Caution**: When both INTP4 and INTSPM are enabled, enable multiple interrupt servicing (before each interrupt request is acknowledged, the EI instruction must be issued.).

**Remarks**: SPOFR: SP overflow address setting register
SPUFR: SP underflow address setting register

![Figure 1-1 INTP4/INTSPM Interrupt Judgement Example](image-url)
1.2 Determination between INTP5 and INTCMP0

Figure 1-2 shows an interrupt processing example in case of both INTP5 (Pin input edge detection 5) and INTCMP0 (Comparator detection 0) are enabled.

Interrupt by INTP5 can be determined from INTFLG01 bit of INTFLG0 (Interrupt source determination flag register 0). And interrupt by INTCMP0 can be determined from INTFLG06 bit of INTFLG0 (Interrupt source determination flag register 0).

![Diagram of INTP5/INTCMP0 Interrupt Judgement Example]

**Figure 1-2 INTP5/INTCMP0 Interrupt Judgement Example**
1.3 Determination between INTP13 and INTCLM

Figure 1-3 shows an interrupt processing example in case of both INTP13 (Pin input edge detection 13) and INTCLM (Main clock or PLL clock stop) are enabled.

Interrupt by INTP13 can be determined from INTFLG07 bit of INTFLG0 (Interrupt source determination flag register 0). And interrupt by INTCLM can be determined from SELPLLS bit of PLLSTS (PLL status register) and SELPLL bit of PLLCTL (PLL control register).

Caution: Be sure to switch the main / PLL selection clock (fMP) to PLL clock frequency (fPLL) before enabling both INTP13 and INTCLM interrupts.

Figure 1-3 INTP13/INTCLM Interrupt Judgement Example
1.4 Determination between INTP8 and INTRTC

Figure 1-4 shows an interrupt processing example in case of both INTP8 (Pin input edge detection 8) and INTRTC (RTC pretimed signal or alarm match detection) are enabled.

Interrupt by INTP8 can be determined from INTFLG02 bit of INTFLG0 (Interrupt source determination flag register 0). And interrupt by INTRTC can be determined from WAFG bit and RIFG bit of RTCC1 (Real-time clock control register 1).

```
INTP8/INTRTC

INTFLG02 == 1?  
(Did INTP8 occur?)

Yes

INTFLG02 = 0;  
(Clear INTFLG02 flag)

INTP8 Processing

RIFG == 1?  
(Did INTRTC (constant-period interrupt) occur?)

Yes

RIFG = 0;  
(Clear RIFG flag)

INTRTC Processing  
(Constant-period interrupt)

WAFG == 1?  
(Did INTRTC (alarm interrupt) occur?)

Yes

WAFG = 0;  
(Clear WAFG flag)

INTRTC Processing  
(RTC alarm interrupt)

return
```

Figure 1-4  INTP8/INTRTC Interrupt Judgement Example
2. Notes on Interrupt Source Determination

2.1 Notes when Clearing bit of INTFLG0 Register

If a new interrupt of the same source occurs during interrupt processing, the interrupt request (IF bit) may become "1" even if the INTFLG0x bit of INTFLG0 register is cleared. In this case, the interrupt is generated, but its interrupt factor INTFLG0x bit is "0" (no interrupt request), so its interrupt is terminated without processing.

The above case will be explained using the INTP4 / INTSPM interrupt as an example. After the INTFLG00 bit is determined to be “1” (INTP4 request is occurred) in the interrupt processing shown in Figure 2-1 and if a new effective edge is input to the INTP4 pin before the INTFLG00 bit is cleared, the PIF4 bit of the IF0L register is set to “1”. After that, the INTFLG00 bit is cleared and the INTP4 interrupt processing ends. And the INTP4 / INTSPM interrupt occurs again as the PIF4 bit is “1”. However, at this time, since the INTFLG00 bit has already been cleared to “0”, the next processing is executed without executing INTP4 Processing.

When using multiple interrupts with them enabled, consider the above notes when designing.

![INTP4/INTSPM Interrupt Judgement Example (INTP4 occurs continuously)](image)

2.2 Notes when Using INTSPM and INTCLM

The CPU stack pointer monitor function or Clock monitor function are a safety function, it is recommended to set those interrupt priority level high.
3. References

Documents referenced in this application note are shown below. When referring to these documents, make sure to obtain the latest version of each document from Renesas Electronics website.

- RL78/ F13, F14 User's Manual: Hardware Rev. 2.10
## Revision History

<table>
<thead>
<tr>
<th>Rev.</th>
<th>Date</th>
<th>Page</th>
<th>Description</th>
<th>Summary</th>
</tr>
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<tbody>
<tr>
<td>1.01</td>
<td>Sep. 30, 2021</td>
<td>-</td>
<td>First edition issued</td>
<td></td>
</tr>
</tbody>
</table>
General Precautions in the Handling of Microprocessing Unit and Microcontroller Unit Products

The following usage notes are applicable to all Microprocessing unit and Microcontroller unit products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Precaution against Electrostatic Discharge (ESD)
   A strong electrical field, when exposed to a CMOS device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop the generation of static electricity as much as possible, and quickly dissipate it when it occurs. Environmental control must be adequate. When it is dry, a humidifier should be used. This is recommended to avoid using insulators that can easily build up static electricity.
   Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work benches and floors must be grounded. The operator must also be grounded using a wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions must be taken for printed circuit boards with mounted semiconductor devices.

2. Processing at power-on
   The state of the product is undefined at the time when power is supplied. The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the time when power is supplied. In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the time when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the time when power is supplied until the power reaches the level at which resetting is specified.

3. Input of signal during power-off state
   Do not input signals or an I/O pull-up power supply while the device is powered off. The current injection that results from input of such a signal or I/O pull-up power supply may cause malfunction and the abnormal current that passes in the device at this time may cause degradation of internal elements. Follow the guideline for input signal during power-off state as described in your product documentation.

4. Handling of unused pins
   Handle unused pins in accordance with the directions given under handling of unused pins in the manual. The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of the LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible.

5. Clock signals
   After applying a reset, only release the reset line after the operating clock signal becomes stable. When switching the clock signal during program execution, wait until the target clock signal is stabilized. When the clock signal is generated with an external resonator or from an external oscillator during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Additionally, when switching to a clock signal produced with an external resonator or by an external oscillator while program execution is in progress, wait until the target clock signal is stable.

6. Voltage application waveform at input pin
   Waveform distortion due to input noise or a reflected wave may cause malfunction. If the input of the CMOS device stays in the area between $V_{IL}(\text{Max})$ and $V_{IH}(\text{Min})$ due to noise, for example, the device may malfunction. Take care to prevent chattering noise from entering the device when the input level is fixed, and also in the transition period when the input level passes through the area between $V_{IL}(\text{Max})$ and $V_{IH}(\text{Min})$.

7. Prohibition of access to reserved addresses
   Access to reserved addresses is prohibited. The reserved addresses are provided for possible future expansion of functions. Do not access these addresses as the correct operation of the LSI is not guaranteed.

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